



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

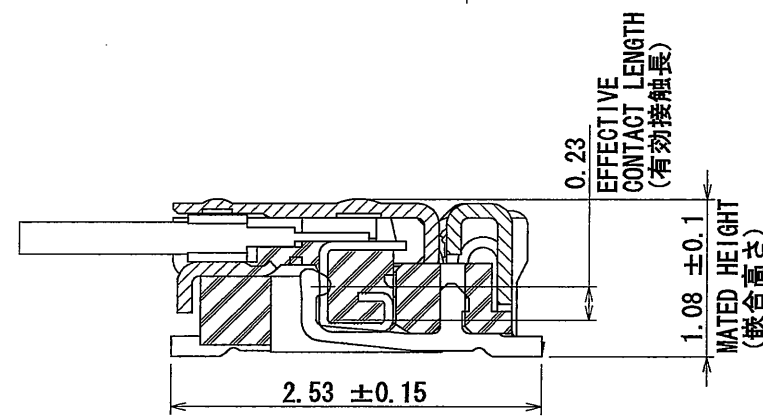
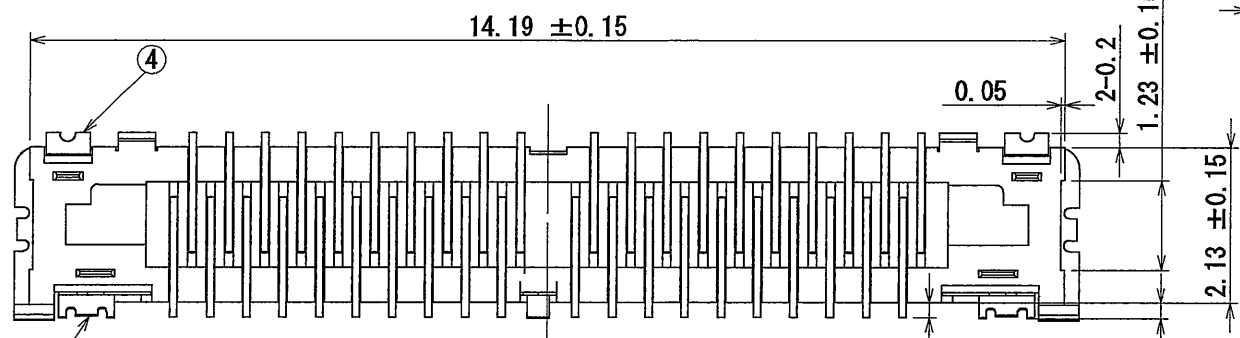
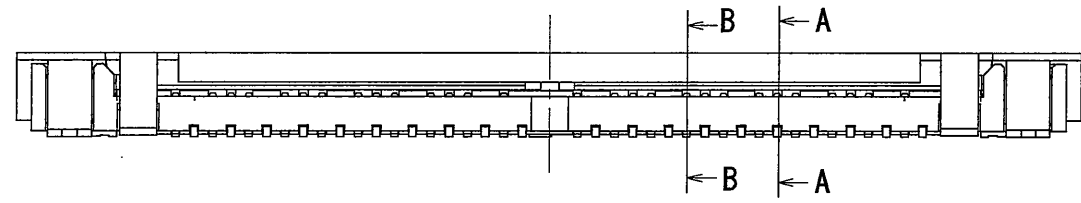
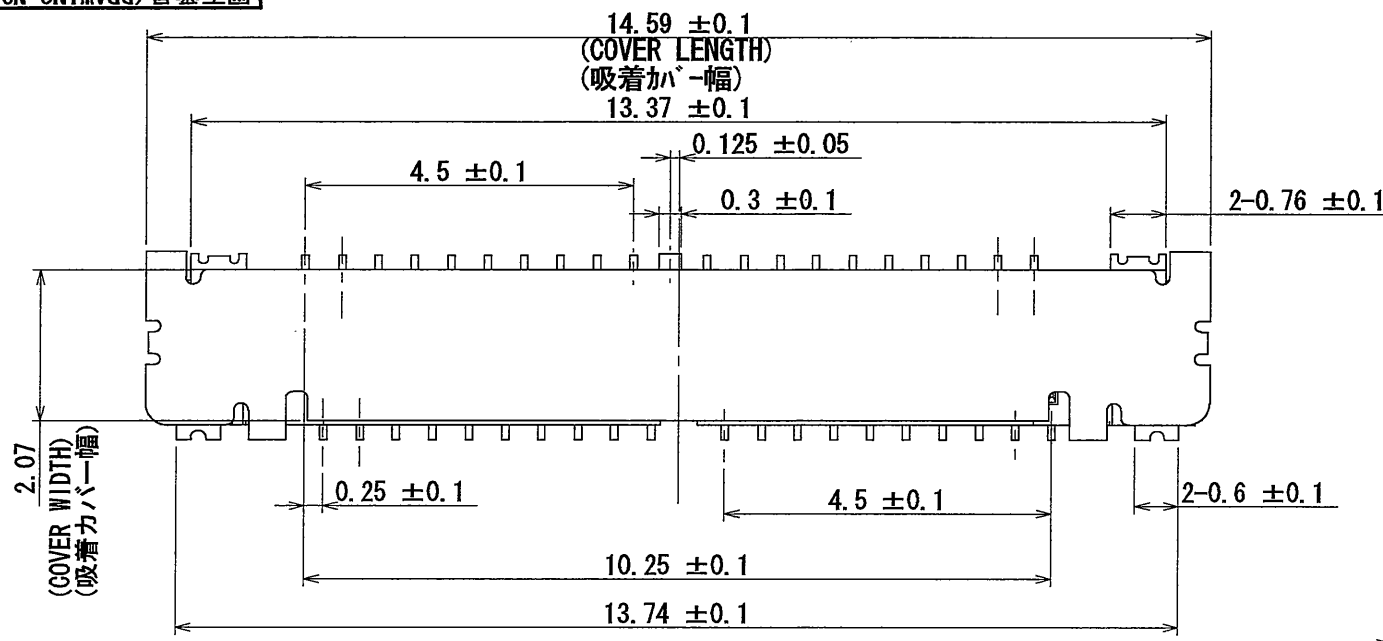


96/601S

(ON DRAWING) 台番号

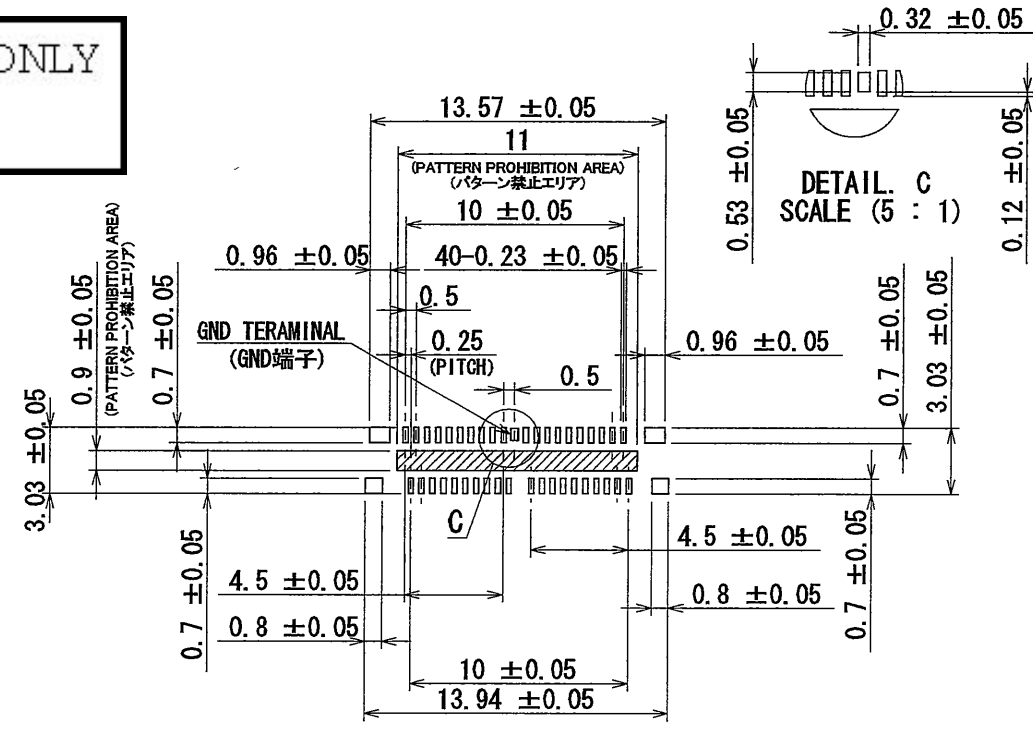
版数 REV.	年月日 DATE	図号 DCN NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.
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REFERENCE ONLY  
**JAE**

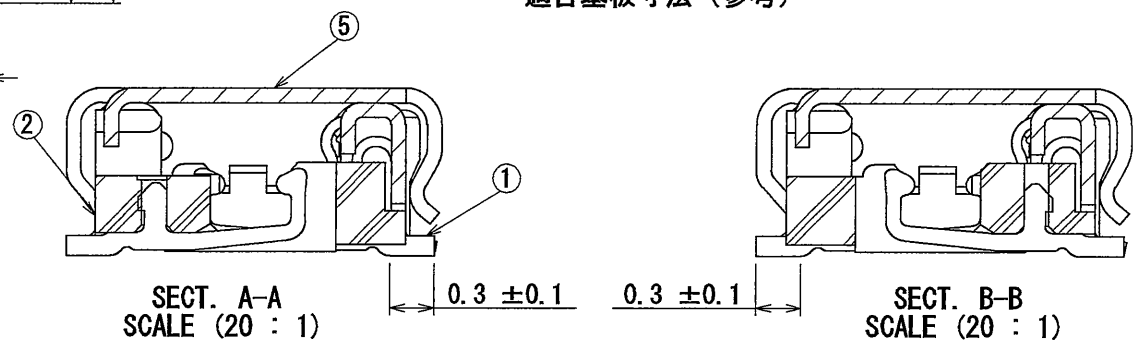


SECT. OF MATED CONDITION (REF.)  
嵌合状態断面図(参考)

NOTE1. COPLANARITY BETWEEN TERMINAL AND HOLD DOWN SHOULD BE 0.1mm MAX.  
注1. 端子及び、ホールドダウンの相互のバラツキは0.1以内とする。



APPLICABLE P.C.B. DIMENSION (REF.)  
適合基板寸法(参考)



符号 NO.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL	仕上 FINISH	図番 DWG NO.
5	VACUUM COVER 吸着カバー	1	STAINLESS STEEL ステンレス	—	—
4	FRONT SHELL フロントシェル	2	COPPER ALLOY 銅合金	GOLD OVER NICKEL Ni上Au	—
3	BACK SHELL バックシェル	1	COPPER ALLOY 銅合金	GOLD OVER NICKEL Ni上Au	—
2	INSULATOR インシュレータ	1	HEAT RESISTING PLASTIC 耐熱性プラスチック	—	UL94 V-0 BLACK 黒
1	CONTACT コンタクト	40	COPPER ALLOY 銅合金	GOLD OVER NICKEL Ni上Au	—

仕様書 (SPECIFICATION)	第1版 (ORIGINAL DATE) 23/JUN/2009	尺度 (SCALE) 10 : 1	シリーズ (SERIES) FI-JP	日本航空電子工業株式会社 JAE JAPAN AVIATION ELECTRONICS INDUSTRY, LTD. 図面番号 (DRAWING NO.) SJ109796	版数 (REV.) 1
一般公差 (GENERAL TOLERANCE)	製図 DR.	名称 (TITLE) FI-JP40S-VF10	質量 (MASS)		
寸法 (DIMENSION)	担当 CHK. K. KAI				
角度 (ANGLES)	査閲 APPD. M. NIKUCHI				
±0.8	承認 APPD. Y. YAHIRO				
× ±0.4					
×× ±0.1					
××× ±					

DF-C-212F (05.08)

